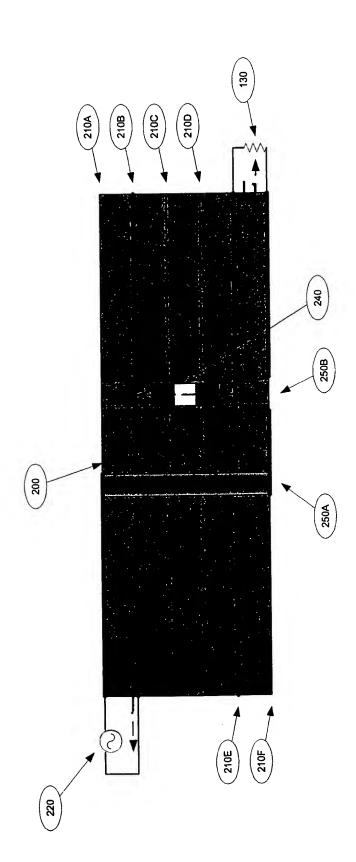


Figure 1 (Prior Art)





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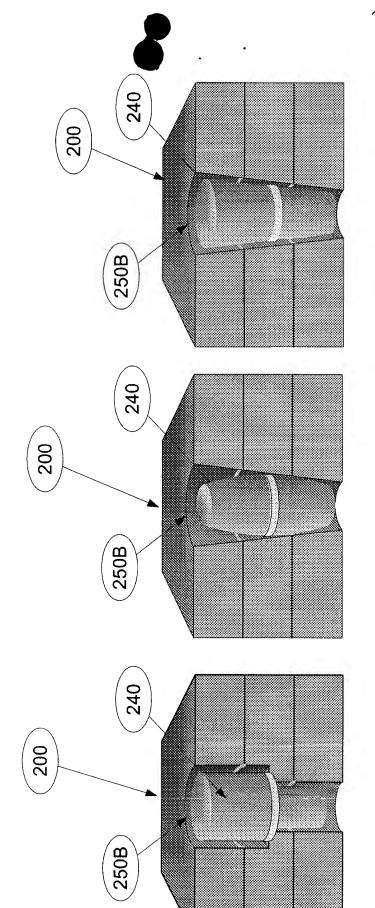


Figure 3A

Figure 3C

Figure 3B

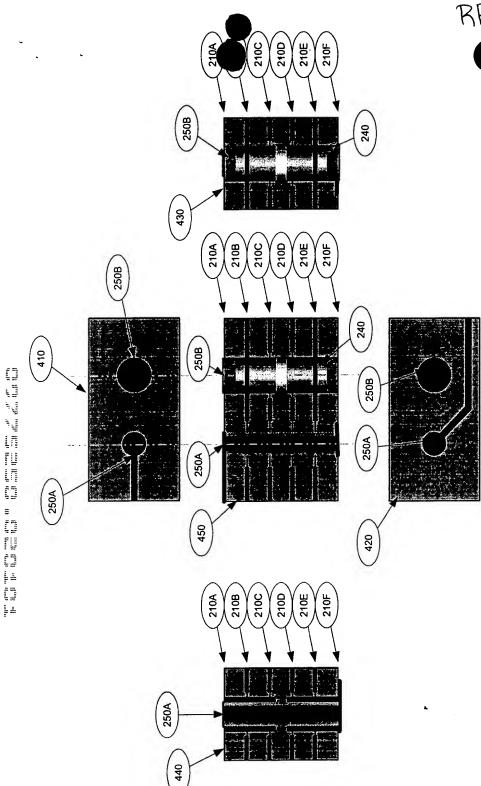


Figure 4

570







500

## Figure 5

Forming a printed circuit board comprising a plurality of conductive layers and two or more vias interconnecting two or more conductive layers of the plurality of conductive layers

520

Embedding an electrical component in the via that forms part of the reference path between two separate inner conductive layers of the plurality of conductive layers within the printed circuit board

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600

## Figure 6

Forming a printed circuit board comprising a plurality of conductive layers and two or more vias interconnecting two or more conductive layers of the plurality of conductive layers

Embedding an electrical component in any particular via between any two separate conductive layers of the plurality of conductive layers within the printed circuit board